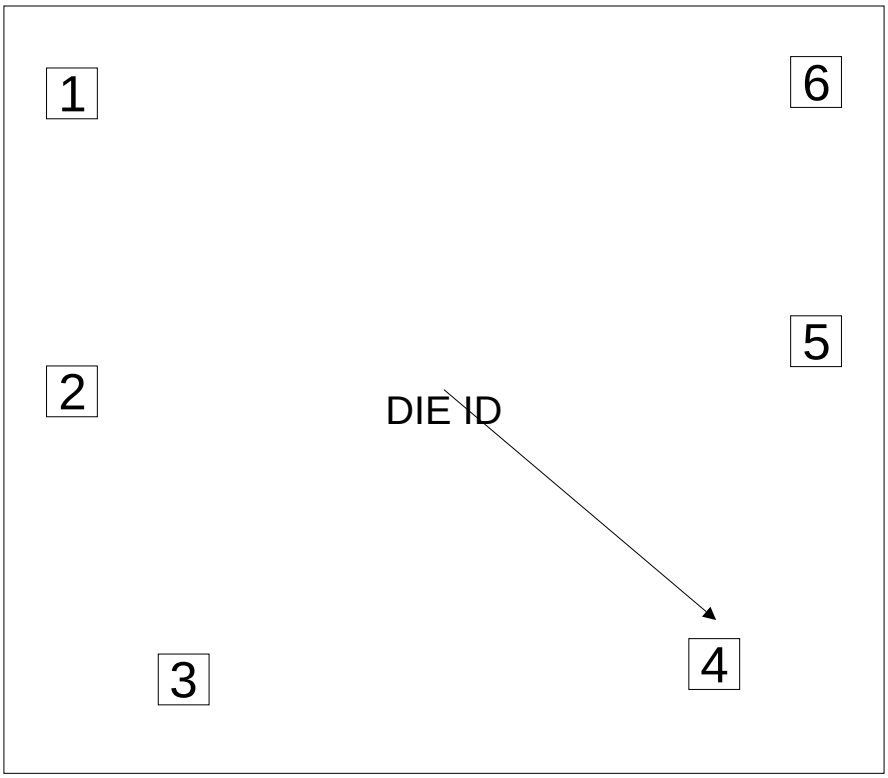
DAC121S101 MDR
12-Bit Micro Power Digital-to-Analog Converter with Rail-to-Rail

AUG 19, 2009

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DAC121S101HR	Bond Pad Opening Size (min)	77.00µm x 77.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	200mm	Back Side Metal	Bare Back
Die Size (Drawn)	1333.50µm x 1163.32µm 52.5mils x 45.8mils	Back Side Connection	Floating or GND
Thickness	304.8µm Nominal		
Min Pitch	392.85µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
VOUT	1	449	564	77	x	77
/SYNC	2	-3	564	77	x	77
SCLK	3	-439	395	77	x	77
DIN	4	-416	-410	77	x	77
GND	5	73	-564	77	x	77
VA	6	466	-564	77	x	77

Notes

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